

ABSTRACT OF THE DISCLOSURE

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10 A method of making a chip resistor is provided. According
to this method, an aggregate board is first prepared which
includes a first region and a second region which are spaced
from each other via an excess portion. Then, a conductor
15 pattern is formed which extends to bridge the first region and
the second region. Subsequently, a resistor element is formed
in each of the first region and the second region for connection
to the conductor pattern. Then, the aggregate board is cut
at the excess portion. The conductor pattern includes a
20 thinner-walled portion extending across the excess portion and
a thicker-walled portion connected to the thinner-walled
portion and spaced from the excess portion.